



Material Content Data Sheet



Halogen-Free

Sales Product Name	IAUC90N10S5N062	Issued	24. February 2022
MA#	MA005707513		
Package	PG-TDSON-8-34	Weight*	112.90 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.413	1.25	1.25	12517	12517
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141	
	non noble metal	iron	7439-89-6	0.053	0.05		469	
	non noble metal	copper	7440-50-8	52.842	46.80	46.86	468057	468667
wire	noble metal	gold	7440-57-5	0.042	0.04	0.04	373	373
encapsulation	organic material	carbon black	1333-86-4	0.075	0.07		661	
	plastics	epoxy resin	-	5.899	5.22		52249	
	inorganic material	silicondioxide	60676-86-0	31.360	27.78	33.07	277780	330690
leadfinish	non noble metal	tin	7440-31-5	1.574	1.39	1.39	13940	13940
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1853	1853
solder	non noble metal	tin	7440-31-5	0.032	0.03		286	
	noble metal	silver	7440-22-4	0.040	0.04		358	
	non noble metal	lead	7439-92-1	1.543	1.37	1.44	13663	14307
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	non noble metal	copper	7440-50-8	16.828	14.91	14.92	149053	149247
clip plating	noble metal	silver	7440-22-4	0.639	0.57	0.57	5660	5660
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.310	0.27	0.27	2742	2746
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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